



Integrated Device Technology, Inc.

CMOS PARALLEL-TO-SERIAL FIFO

256 x 16, 512 x 16, 1,024 x 16

IDT72105
IDT72115
IDT72125

FEATURES:

- 25ns parallel port access time, 35ns cycle time
- 45MHz serial output shift rate
- Wide x16 organization offering easy expansion
- Low power consumption (50mA typical)
- Least/Most Significant Bit first read selected by asserting the FL/DIR pin
- Four memory status flags: Empty, Full, Half-Full, and Almost-Empty/Almost-Full
- Dual-Port zero fall-through architecture
- Available in 28-pin 300 mil plastic DIP and 28-pin SOIC
- Industrial temperature range (-40°C to +85°C)

DESCRIPTION:

The IDT72105/72115/72125s are very high-speed, low-power, dedicated, parallel-to-serial FIFOs. These FIFOs possess a 16-bit parallel input port and a serial output port with 256, 512 and 1,024 word depths, respectively.

The ability to buffer wide word widths (x16) make these FIFOs ideal for laser printers, FAX machines, local area

networks (LANs), video storage and disk/tape controller applications.

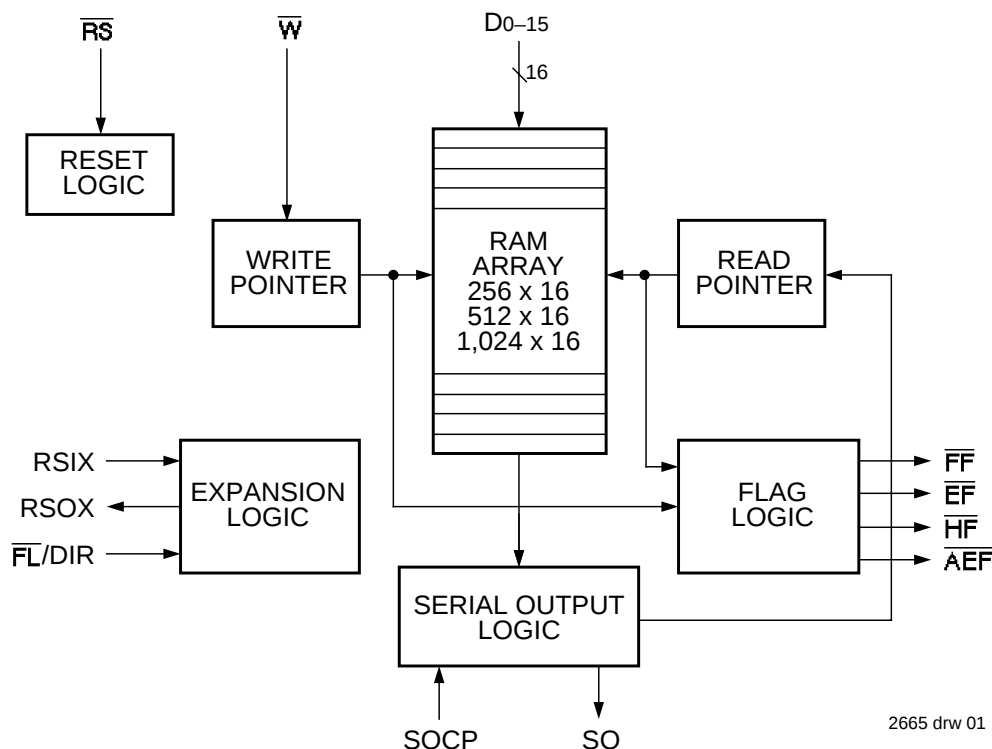
Expansion in width and depth can be achieved using multiple chips. IDT's unique serial expansion logic makes this possible using a minimum of pins.

The unique serial output port is driven by one data pin (SO) and one clock pin (SOCP). The Least Significant or Most Significant Bit can be read first by programming the DIR pin after a reset.

Monitoring the FIFO is eased by the availability of four status flags: Empty, Full, Half-Full and Almost-Empty/Almost-Full. The Full and Empty flags prevent any FIFO data overflow or underflow conditions. The Half-Full Flag is available in both single and expansion mode configurations. The Almost-Empty/Almost-Full Flag is available only in a single device mode.

The IDT72105/72115/72125 are fabricated using IDT's leading edge, submicron CMOS technology. Military grade product is manufactured in compliance with the latest revision of Mil-STD-883, Class B.

FUNCTIONAL BLOCK DIAGRAM



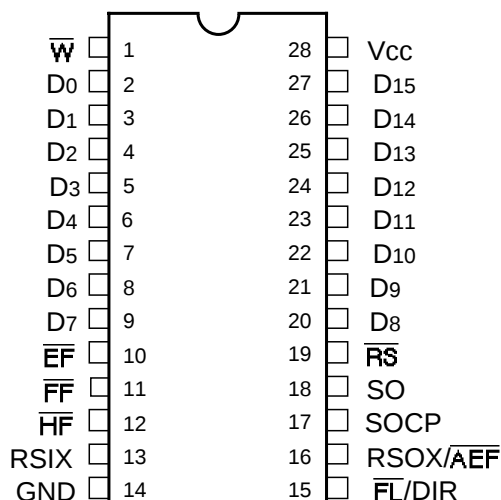
2665 drw 01

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FAST is a trademark of National Semiconductor Co.

INDUSTRIAL TEMPERATURE RANGE

DECEMBER 1999

PIN CONFIGURATION



2665 drw 02

PLASTIC THIN DIP (P28-2, order code: TP)

SOIC (SO28-3, order code: SO)

TOP VIEW

PIN DESCRIPTIONS

Symbol	Name	I/O	Description
D0–D15	Inputs	I	Data inputs for 16-bit wide data.
$\overline{RS}$	Reset	I	When $\overline{RS}$ is set low, internal READ and WRITE pointers are set to the first location of the RAM array. $\overline{FF}$ and $\overline{HF}$ go HIGH. $\overline{EF}$ and $\overline{AEF}$ go LOW. A reset is required before an initial WRITE after power-up. $\overline{W}$ must be high during the $\overline{RS}$ cycle. Also the First Load pin ($\overline{FL}$) is programmed only during Reset.
$\overline{W}$	Write	I	A write cycle is initiated on the falling edge of WRITE if the Full Flag ($\overline{FF}$) is not set. Data set-up and hold times must be adhered to with respect to the rising edge of WRITE. Data is stored in the RAM array sequentially and independently of any ongoing read operation.
SOCP	Serial Output Clock	I	A serial bit read cycle is initiated on the rising edge of SOCP if the Empty Flag ($\overline{EF}$) is not set. In both Depth and Serial Word Width Expansion modes, all of the SOCP pins are tied together.
$\overline{FL}/\overline{DIR}$	First Load/Direction	I	This is a dual purpose input used in the width and depth expansion configurations. The First Load ($\overline{FL}$) function is programmed only during Reset ($\overline{RS}$) and a LOW on $\overline{FL}$ indicates the first device to be loaded with a byte of data. All other devices should be programmed HIGH. The Direction ($\overline{DIR}$) pin controls shift direction after Reset and tells the device whether to read out the Least Significant or Most Significant bit first.
RSIX	Read Serial In Expansion	I	In the single device configuration, RSIX is set HIGH. In depth expansion or daisy chain expansion, RSIX is connected to RSOX (expansion out) of the previous device.
SO	Serial Output	O	Serial data is output on the Serial Output (SO) pin. Data is clocked out LSB or MSB depending on the Direction pin programming. During Expansion the SO pins are tied together.
$\overline{FF}$	Full Flag	O	When $\overline{FF}$ goes LOW, the device is full and further WRITE operations are inhibited. When $\overline{FF}$ is HIGH, the device is not full.
$\overline{EF}$	Empty Flag	O	When $\overline{EF}$ goes LOW, the device is empty and further READ operations are inhibited. When $\overline{EF}$ is HIGH, the device is not empty.
$\overline{HF}$	Half-Full Flag	O	When $\overline{HF}$ is LOW, the device is more than half-full. When $\overline{HF}$ is HIGH, the device is empty to half-full.
RSOX/ $\overline{AEF}$	Read Serial Out Expansion Almost-Empty, Almost-Full Flag	O	This is a dual purpose output. In the single device configuration ($\overline{RSIX}$ HIGH), this is an $\overline{AEF}$ output pin. When $\overline{AEF}$ is LOW, the device is empty-to-(1/8 full -1) or (7/8 full +1)-to-full. When $\overline{AEF}$ is HIGH, the device is 1/8-full up to 7/8-full. In the Expansion configuration ($\overline{RSOX}$ connected to $\overline{RSIX}$ of the next device) a pulse is sent from RSOX to $\overline{RSIX}$ to coordinate the width, depth or daisy chain expansion.
Vcc	Power Supply		Single power supply of 5V.
GND	Ground		Single ground of 0V.

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STATUS FLAGS

Number of Words in FIFO			$\overline{FF}$	$\overline{AEF}$	$\overline{HF}$	$\overline{EF}$
IDT72105	IDT72115	IDT72125				
0	0	0	H	L	H	L
1–31	1–63	1–127	H	L	H	H
32–128	64–256	128–512	H	H	H	H
129–224	257–448	513–896	H	H	L	H
225–255	449–511	897–1023	H	L	L	H
256	512	1024	L	L	L	H

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Commercial	Unit
VTERM	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
TSTG	Storage Temperature	–55 to +125	°C
IOUT	DC Output Current	–50 to +50	mA

NOTE: 2665 tbl 03

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
VCC	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
VIH	Input HIGH Voltage	2.0	—	—	V
VIL ⁽¹⁾	Input LOW Voltage	—	—	0.8	V
TA	Operating Temperature	–40	—	+85	°C

NOTE: 2665 tbl 04

- 1.5V undershoots are allowed for 10ns once per cycle.

DC ELECTRICAL CHARACTERISTICS

(Industrial: VCC = 5.0V ± 10%, TA = –40°C to +85°C)

Symbol	Parameter	IDT72105 IDT72115 IDT72125 Industrial			Unit
		Min.	Typ.	Max.	
ILI ⁽¹⁾	Input Leakage Current (Any Input)	–1	—	1	μA
ILO ⁽²⁾	Output Leakage Current	–10	—	10	μA
VOH	Output Logic "1" Voltage IOUT = –2mA ⁽³⁾	2.4	—	—	V
VOL	Output Logic "0" Voltage IOUT = 8mA ⁽⁴⁾	—	—	0.4	V
ICC1 ⁽⁵⁾	Active Power Supply Current	—	50	100	mA
ICC2 ^(5,6,7)	Standby Current ($\overline{W} = \overline{RS} = \overline{FL}/\overline{DIR} = V_{IH}$; SOCP = VIL)	—	4	8	mA
ICC3 ^(5,6,7)	Power Down Current	—	1	6	mA

NOTES:

- Measurements with $0.4V \leq V_{IN} \leq V_{CC}$.
- SOCP = VIL, $0.4 \leq V_{OUT} \leq V_{CC}$.
- For SO, IOUT = –4mA.
- For SO, IOUT = 16mA.
- Tested with outputs open (IOUT = 0).
- RS = FL/DIR = W = VCC – 0.2V; SOCP = 0.2V; all other inputs = VCC – 0.2.
- Measurements are made after reset.

2665 tbl 05

AC ELECTRICAL CHARACTERISTICS

(Industrial: VCC = 5V±10%, TA = -40°C to +85°C)

Symbol	Parameter	Figure	INDUSTRIAL				Unit
			72105L25 72115L25 72125L25		72105L50 72115L50 72125L50		
			Min.	Max.	Min.	Max.	
ts	Parallel Shift Frequency	—	—	28.5	—	15	MHz
tsOCP	Serial Shift Frequency	—	—	50	—	40	MHz
PARALLEL INPUT TIMINGS							
tWC	Write Cycle Time	2	35	—	65	—	ns
tWPW	Write Pulse Width	2	25	—	50	—	ns
tWR	Write Recovery Time	2	10	—	15	—	ns
tDS	Data Set-up Time	2	12	—	15	—	ns
tDH	Data Hold Time	2	0	—	2	—	ns
tWEF	Write High to $\overline{EF}$ HIGH	5, 6	—	35	—	45	ns
tWFF	Write Low to $\overline{FF}$ LOW	4, 7	—	35	—	45	ns
tWF	Write Low to Transitioning $\overline{HF}$, $\overline{AEF}$	8	—	35	—	45	ns
tWPF	Write Pulse Width After $\overline{FF}$ HIGH	7	25	—	50	—	ns
SERIAL OUTPUT TIMINGS							
tsOCP	Serial Clock Cycle Time	3	20	—	25	—	ns
tsOCW	Serial Clock Width HIGH/LOW	3	8	—	10	—	ns
tsOPD	SOCP Rising Edge to SO Valid Data	3	—	14	—	15	ns
tSOHZ	SOCP Rising Edge to SO at High-Z ⁽¹⁾	3	3	14	3	15	ns
tsOLZ	SOCP Rising Edge to SO at Low-Z ⁽¹⁾	3	3	14	3	15	ns
tsOCEF	SOCP Rising Edge to $\overline{EF}$ LOW	5, 6	—	35	—	45	ns
tsOCFF	SOCP Rising Edge to $\overline{FF}$ HIGH	4, 7	—	35	—	45	ns
tsOCF	SOCP Rising Edge to Transitioning $\overline{HF}$, $\overline{AEF}$	8	—	35	—	45	ns
tREFSO	SOCP Delay After $\overline{EF}$ HIGH	6	35	—	65	—	ns
RESET TIMINGS							
trSC	Reset Cycle Time	1	35	—	65	—	ns
trS	Reset Pulse Width	1	25	—	50	—	ns
trSS	Reset Set-up Time	1	25	—	50	—	ns
trSR	Reset Recovery Time	1	10	—	15	—	ns
EXPANSION MODE TIMINGS							
tFLS	$\overline{FL}$ Set-up Time to $\overline{RS}$ Rising Edge	9	7	—	8	—	ns
tFLH	$\overline{FL}$ Hold Time to $\overline{RS}$ Rising Edge	9	0	—	2	—	ns
tDIRS	DIR Set-up Time to SOCP Rising Edge	9	10	—	12	—	ns
tDIRH	DIR Hold Time from SOCP Rising Edge	9	5	—	5	—	ns
tsOXD1	SOCP Rising Edge to RSOX Rising Edge	9	—	15	—	17	ns
tsOXD2	SOCP Rising Edge to RSOX Falling Edge	9	—	15	—	17	ns
tsIXS	RSIX Set-up Time to SOCP Rising Edge	9	5	—	8	—	ns
tsIXPW	RSIX Pulse Width	9	10	—	15	—	ns

NOTE:

1. Values guaranteed by design.

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figure A

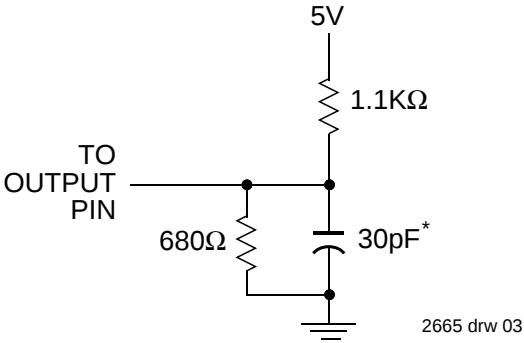
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CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 0V	10	pF
COUT	Output Capacitance	VOUT = 0V	12	pF

NOTE: 2665 tbl 08

1. Characterized values, not currently tested.



or equivalent circuit

Figure A. Output Load

*Includes jig and scope capacitances.

FUNCTIONAL DESCRIPTION

Parallel Data Input

The device must be reset before beginning operation so that all flags are set to their initial state. In width or depth expansion the First Load pin (FL) must be programmed to indicate the first device.

The data is written into the FIFO in parallel through the Do-15 input data lines. A write cycle is initiated on the falling edge of the Write ($\overline{W}$) signal provided the Full Flag (FF) is not asserted. If the $\overline{W}$ signal changes from HIGH-to-LOW and the Full Flag (FF) is already set, the write line is internally inhibited from incrementing the write pointer and no write operation occurs.

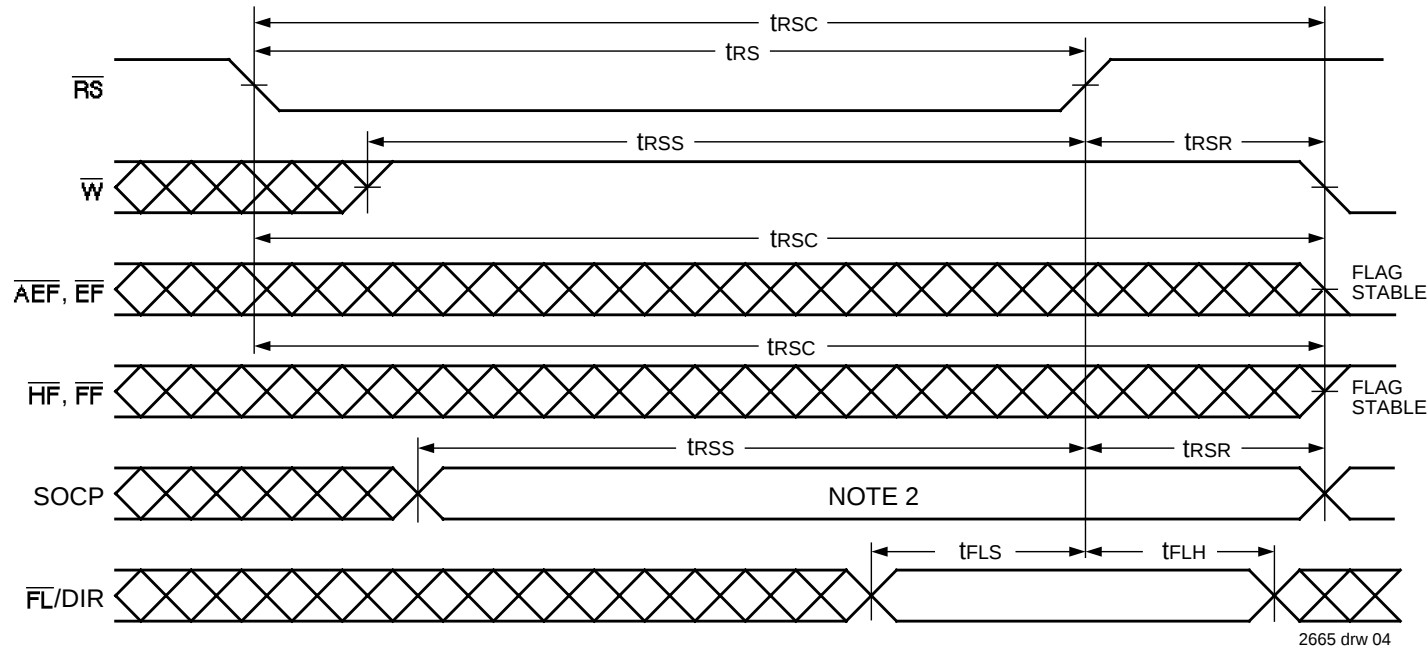
Data set-up and hold times must be met with respect to the rising edge of Write. On the rising edge of $\overline{W}$, the write pointer

is incremented. Write operations can occur simultaneously or asynchronously with read operations.

Serial Data Output

The serial data is output on the SO pin. The data is clocked out on the rising edge of SOCP providing the Empty Flag (EF) is not asserted. If the Empty Flag is asserted then the next data word is inhibited from moving to the output register and being clocked out by SOCP.

The serial word is shifted out Least Significant Bit or Most Significant Bit first, depending on the FL/DIR level during operation. A LOW on DIR will cause the Least Significant Bit to be read out first. A HIGH on DIR will cause the Most Significant Bit to be read out first.



NOTES:

1. EF, FF, HF and AEF may change status during Reset, but flags will be valid at trsc.
2. SOCP should be in the steady LOW or HIGH during trss. The first LOW-HIGH (or HIGH-LOW) transition can begin after trsr.

Figure 1. Reset

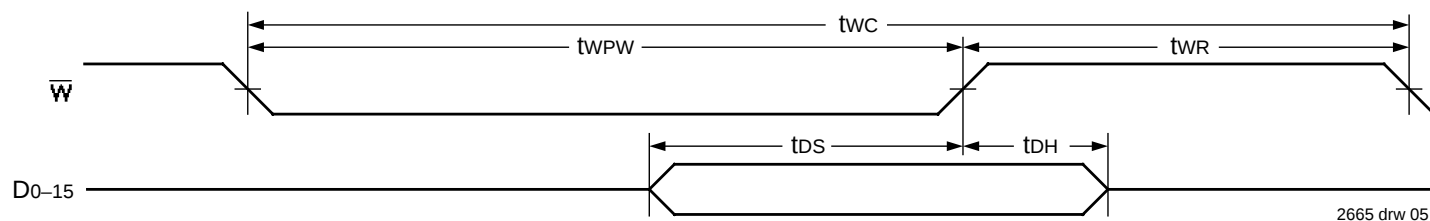
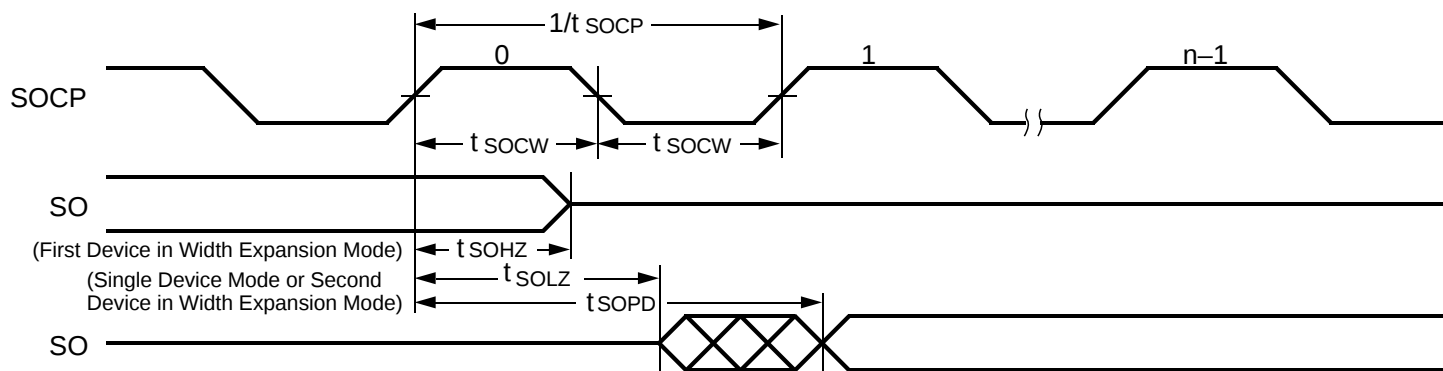


Figure 2. Write Operation



NOTE:

1. In Single Device Mode, SO will not tri-state except after reset.

Figure 3. Read Operation

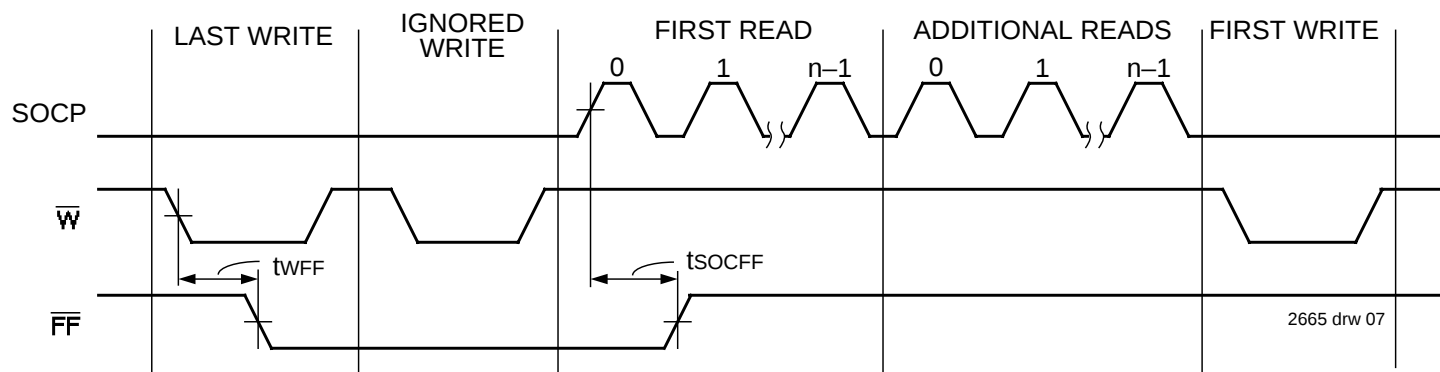
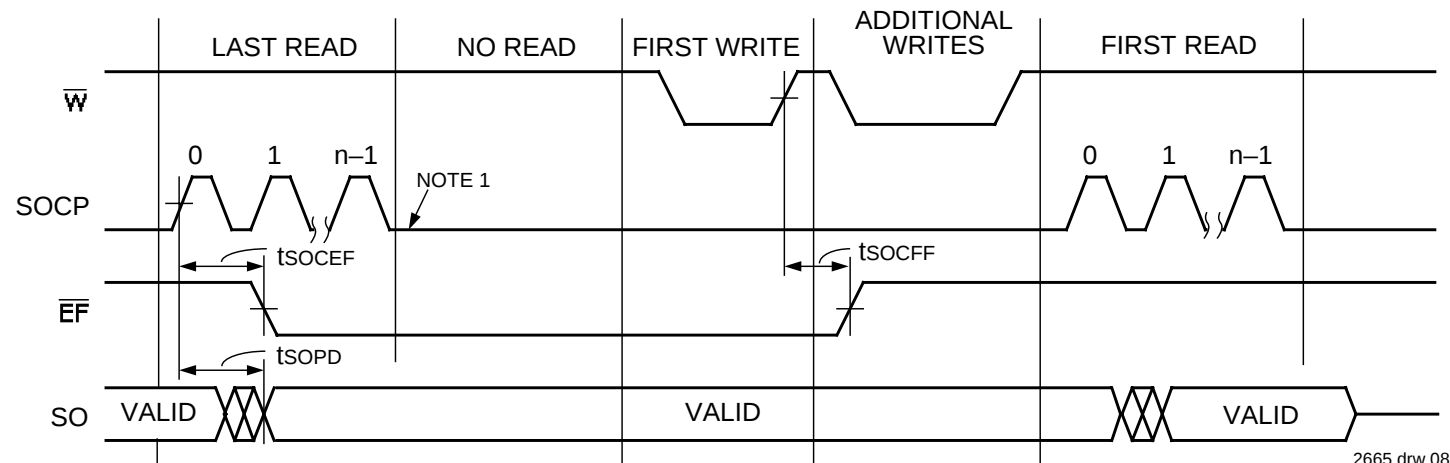


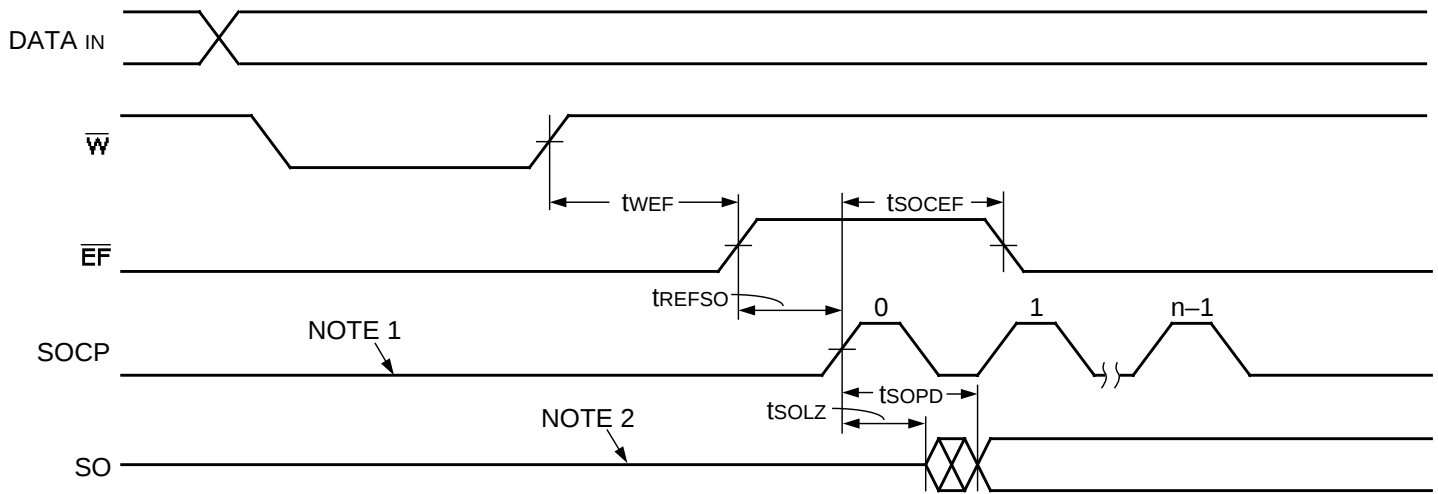
Figure 4. Full Flag from Last Write to First Read



NOTE:

1. SOCP should not be clocked until EF goes HIGH.

Figure 5. Empty Flag from Last Read to First Write

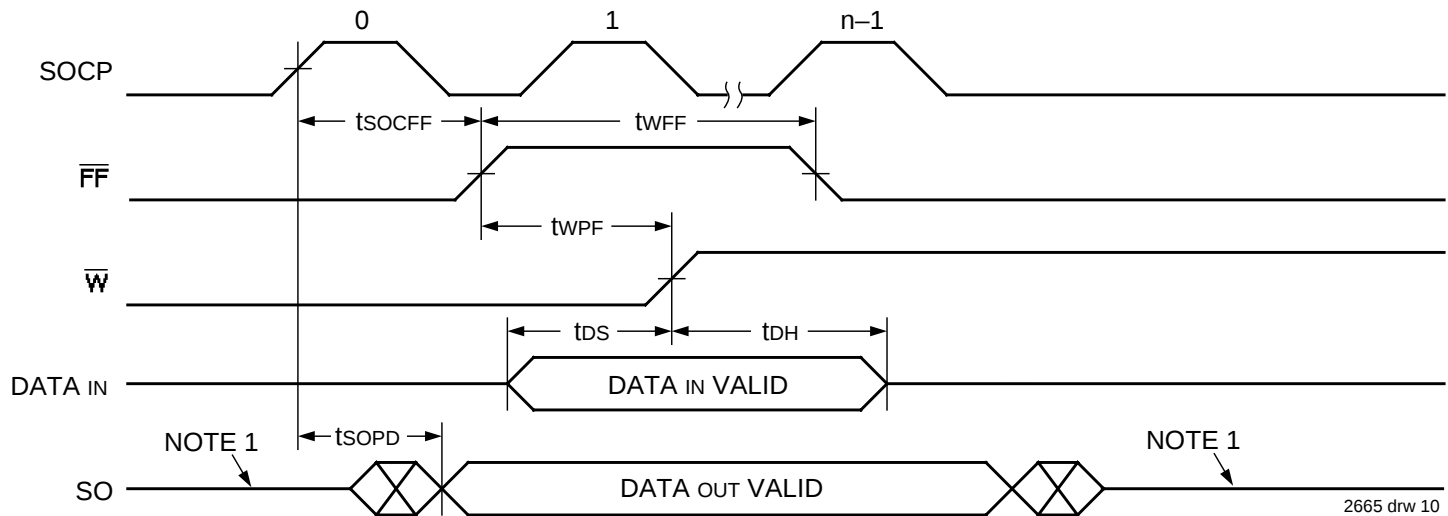


NOTES:

1. Once $\overline{EF}$ has gone LOW and the last bit of the final word has been shifted out, SOCP should not be clocked until $\overline{EF}$ goes HIGH.
2. In Single Device Mode, SO will not tri-state except after Reset. It will retain the last valid data.

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Figure 6. Empty Boundary Condition Timing

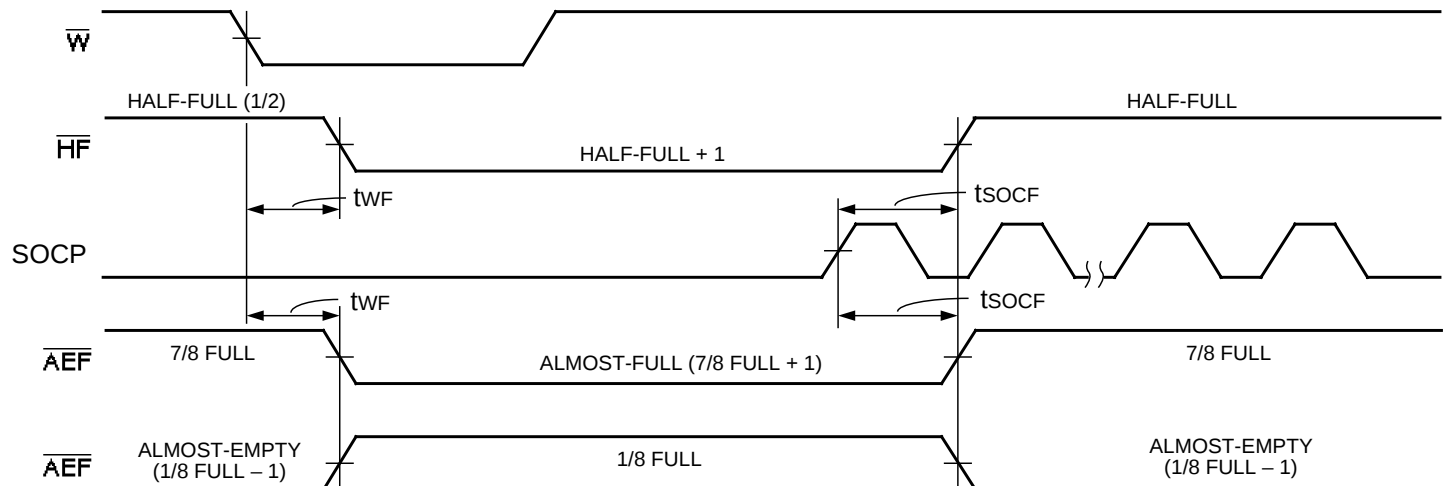


NOTE:

1. Single Device Mode will not tri-state but will retain the last valid data.

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Figure 7. Full Boundary Condition Timing



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Figure 8. Half-Full, Almost-Full and Almost-Empty Timings

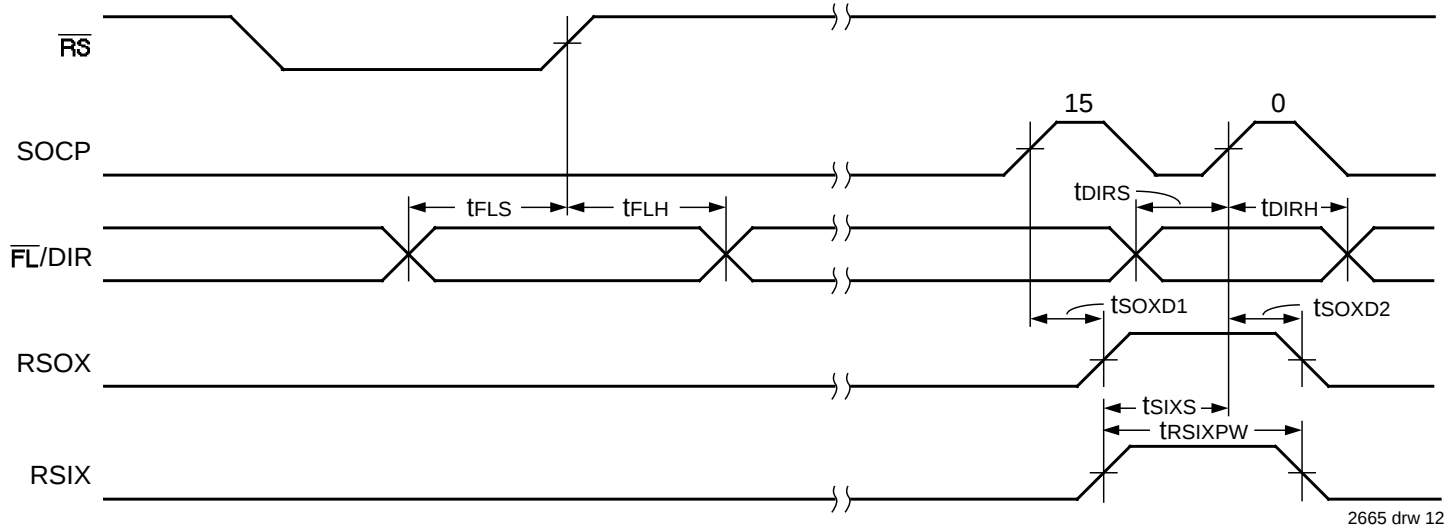


Figure 9. Serial Read Expansion

OPERATING CONFIGURATIONS

Single Device Mode

The device must be reset before beginning operation so that all flags are set to location zero. In the standalone case, the RSIX line is tied HIGH and indicates single device operation to the device. The RSOX/ĀEF pin defaults to ĀEF and outputs the Almost-Empty and Almost-Full Flag.

Width Expansion Mode

In the cascaded case, word widths of more than 16 bits can be achieved by using more than one device. By tying the RSOX and RSIX pins together, as shown in Figure 11, and programming which is the Least Significant Device, a cascaded serial word is achieved. The Least Significant Device is programmed by a LOW on the FL/DIR pin during reset. All other devices should be programmed HIGH on the FL/DIR pin at reset.

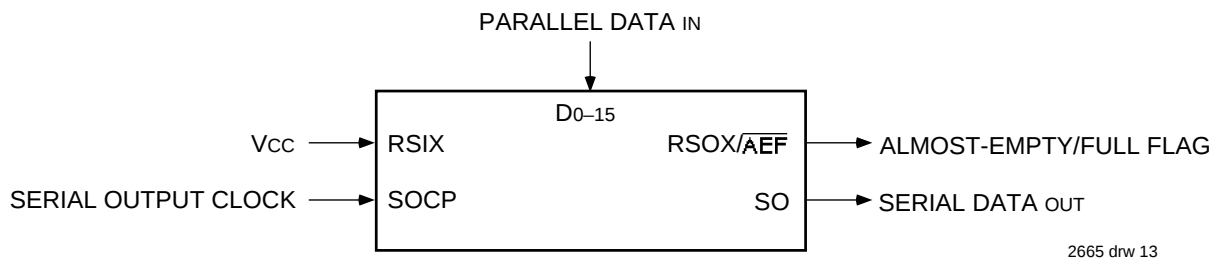


Figure 10. Single Device Configuration

Mode	Inputs			Internal Status		Outputs		
	RS	FL	DIR	Read Pointer	Write Pointer	ĀEF, ĒF	FF	HF
Reset	0	X	X	Location Zero	Location Zero	0	1	1
Read/Write	1	X	0,1	Increment ⁽¹⁾	Increment ⁽¹⁾	X	X	X

NOTE:

1. Pointer will increment if appropriate flag is HIGH.

2665 tbi 09

Table 1. Reset and First Load Truth Table—Single Device Configuration

The Serial Data Output (SO) of each device in the serial word must be tied together. Since the SO pin is three stated, only the device which is currently shifting out is enabled and driving the 1-bit bus. NOTE: After reset, the level on the FL/DIR pin decides if the Least Significant or Most Significant Bit is read first out of each device.

The three flag outputs, Empty (ĒF), Half-Full (HF) and Full (FF), should be taken from the Most Significant Device (in the example, FIFO #2). The Almost-Empty/Almost-Full flag is not available. The RSOX pin is used for expansion.

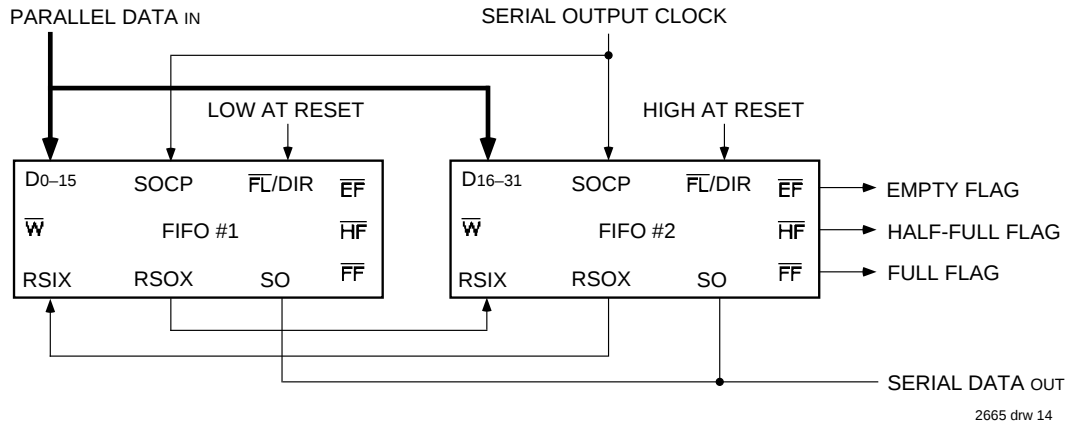


Figure 11. Width Expansion for 32-bit Parallel Data In

Depth Expansion (Daisy Chain) Mode

The IDT72105/72115/72125 can easily be adapted to applications requiring greater than 1,024 words. Figure 12 demonstrates Depth Expansion using three IDT72105/72115/72125s and an IDT74FCT138 Address Decoder. Any depth can be attained by adding additional devices. The Address Decoder is necessary to determine which FIFO is being written. A word of data must be written sequentially into each FIFO so that the data will be read in the correct sequence. These devices operate in the Depth Expansion Mode when the following conditions are met:

1. The first device must be programmed by holding $\overline{\text{FL}}$ LOW at Reset. All other devices must be programmed by holding $\overline{\text{FL}}$ HIGH at reset.
2. The Read Serial Out Expansion pin (RSOX) of each device must be tied to the Read Serial In Expansion pin (RSIX) of the next device (see Figure 12).

3. External logic is needed to generate composite Empty, Half-Full and Full Flags. This requires the ORing of all EF, HF and FF Flags.
4. The Almost-Empty and Almost-Full Flag is not available due to using the RSOX pin for expansion.

Compound Expansion (Daisy Chain) Mode

These FIFOs can be expanded in both depth and width as Figure 13 indicates:

1. The RSOX-to-RSIX expansion signals are wrapped around sequentially.
2. The write ($\overline{\text{W}}$) signal is expanded in width.
3. Flag signals are only taken from the Most Significant Devices.
4. The Least Significant Device in the array must be programmed with a LOW on $\overline{\text{FL/DIR}}$ during reset.

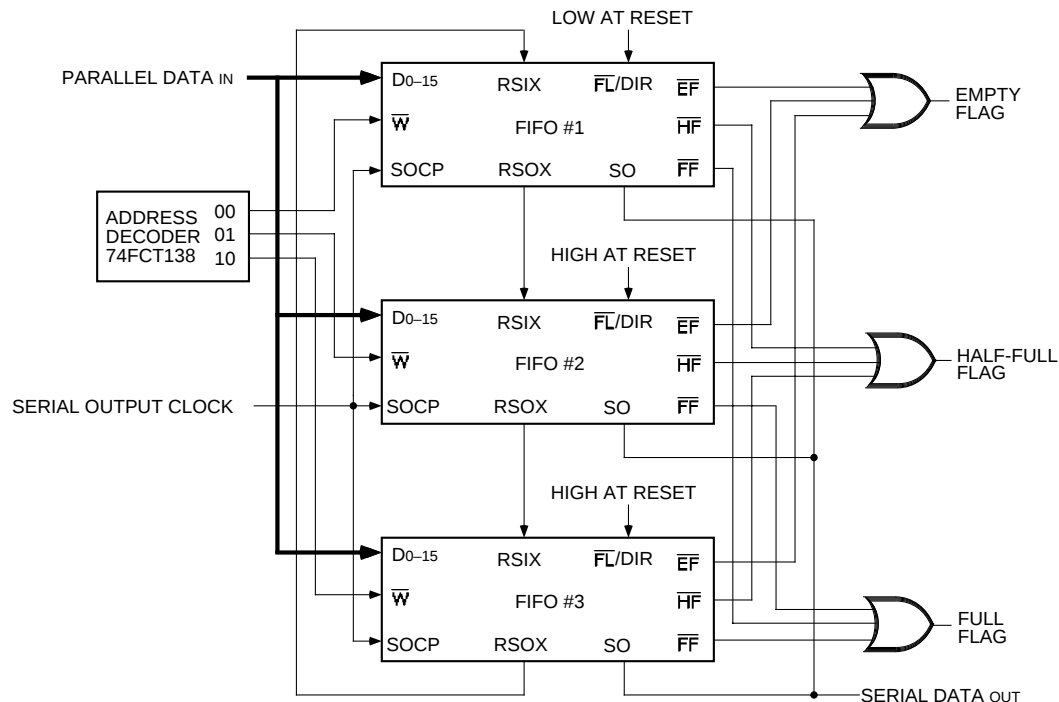


Figure 12. A 3K x 16 Parallel-to-Serial FIFO using the IDT72125

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Mode	Inputs			Internal Status		Outputs	
	$\overline{RS}$	$\overline{FL}$	DIR	Read Pointer	Write Pointer	$\overline{EF}$	$\overline{HF}$, $\overline{FF}$
Reset-First Device	0	0	X	Location Zero	Location Zero	0	1
Reset All Other Devices	0	1	X	Location Zero	Location Zero	0	1
Read/Write	1	X	0,1	X	X	X	X

NOTE:

1. $\overline{RS}$ = Reset Input, $\overline{FL}/\overline{FIR}$ = First Load/Direction, $\overline{EF}$ = Empty Flag Output, $\overline{HF}$ = Half- Full Flag Output, $\overline{FF}$ = Full Flag Output.

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Table 2. Reset and First Load Truth Table–Width/Depth Compound Expansion Mode

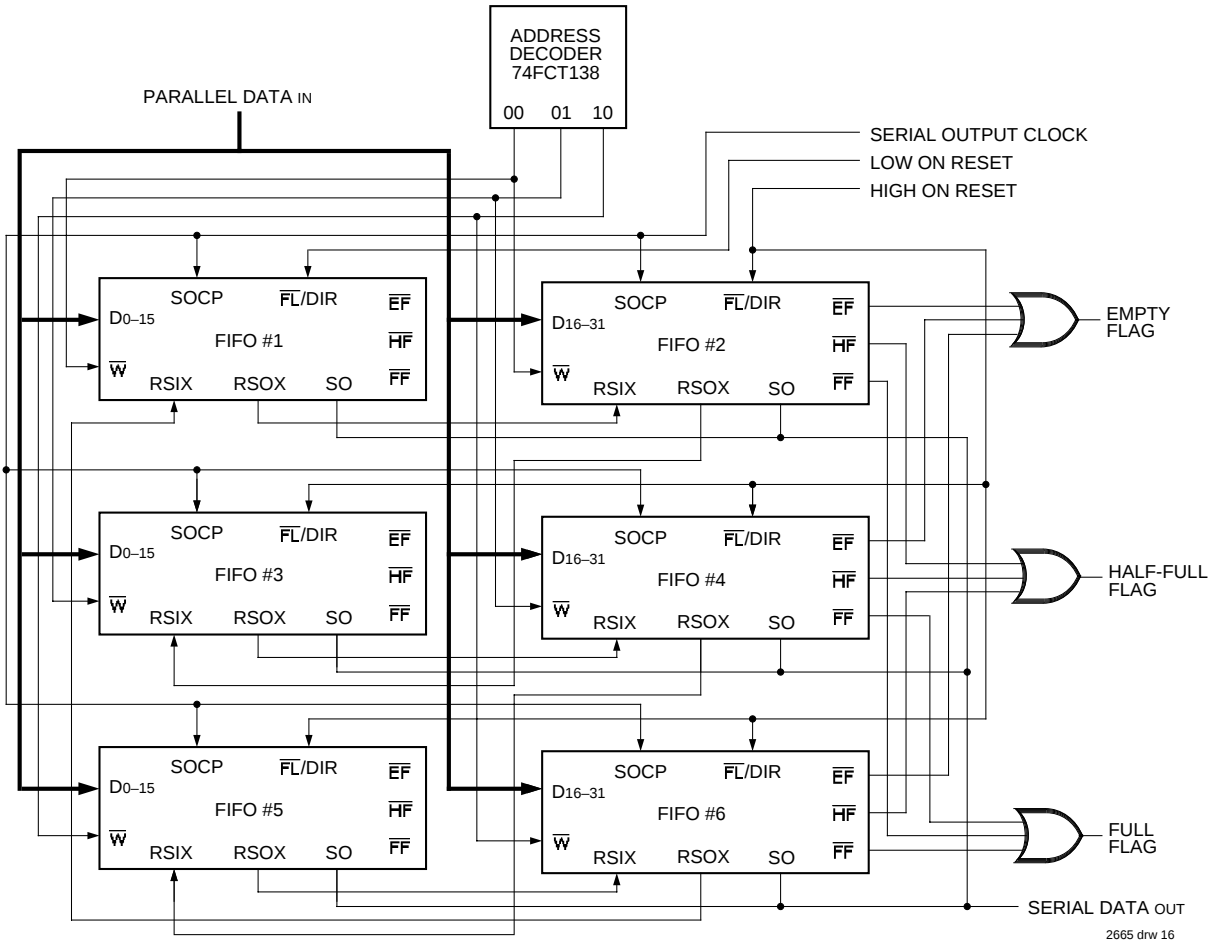


Figure 13. A 3K x 32 Parallel-to-Serial FIFO using the IDT72125

ORDERING INFORMATION

IDT	XXXXX	X	XX	X	X	
DeviceType	Power	Speed	Package	Process/ Temperature Range		
				BLANK	Industrial (-40°C to +85°C)	
				TP	Plastic Thin DIP (300mil, P28-2)	
				SO	Small Outline IC (Gull Wing, SOIC, SO28-3)	
		25			(50 MHz serial shift rate)	} Parallel Access Time (t _A) in Nanoseconds
		50			(40MHz serial shift rate)	
		L			Low Power	
				72105	256 x 16-Bit Parallel-to-Serial FIFO	
				72115	512 x 16-Bit Parallel-to-Serial FIFO	
				72125	1,024 x 16-Bit Parallel-to-Serial FIFO	

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